

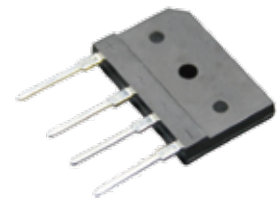
FEATURES

- | Ideal For Printed Circuit Board Mounting

- | Built-in Printed Circuit Board Stand-offs

- | The Plastic Material Used Carries Underwriters Laboratory
Flammability Recognition 94V-0

- | High Case Dielectric Strength



GBJ

MECHANICAL DATA

- | Case: Reliable Low Cost Construction Utilizing Molded
Plastic Technique

- | Mounting Position: Any

APPROVALS

RoHS Compliance with 2011/65/EU

MAXIMUM RATINGS AND CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	GBJ 50005	GBJ 5001	GBJ 5002	GBJ 5004	GBJ 5006	GBJ 5008	GBJ 5010	Unit
Marking		GBJ 50005	GBJ 5001	GBJ 5002	GBJ 5004	GBJ 5006	GBJ 5008	GBJ 5010	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	v
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward (With Heatsink Note1) Rectified Current At Tc=100°C	I _{F(AV)}	50.0							A
Peak Forward Surge Current Single Sine-wave Superimposed On Rated Load (JEDEC Method)	I _{FSM}	500							A
Rating For Fusing (T<8.3ms)	I ² t	1037							A ² sec
Maximum Instantaneous Forward Voltage Drop Per Leg at 25.0A	V _F	1.1							V
Maximum DC Reverse Current At Rated DC Blocking Voltage Per Diode	T _A =25°C	10							μA
	T _A =125°C	500							μA
Operating Junction And Storage Temperature Range	T _J , T _{STG}	-55 ~ +150							°C

Notes: (1) Device mounted on 300mm*300mm*1.6mm cu plate heatsink

CHARACTERISTIC CURVES

Fig. 1-Forward Current Derating Curve

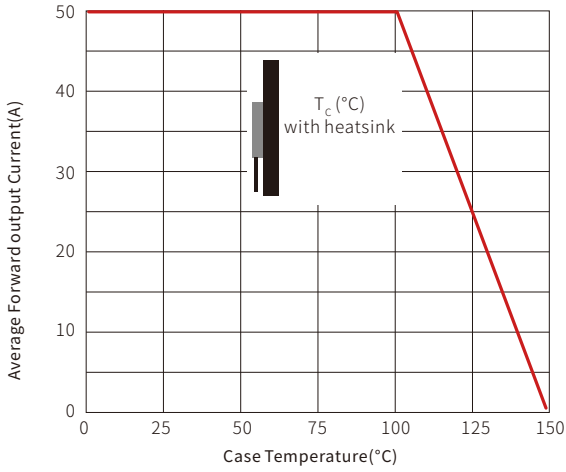


Fig. 2-Maximum Non-Repetitive Peak Surge Current

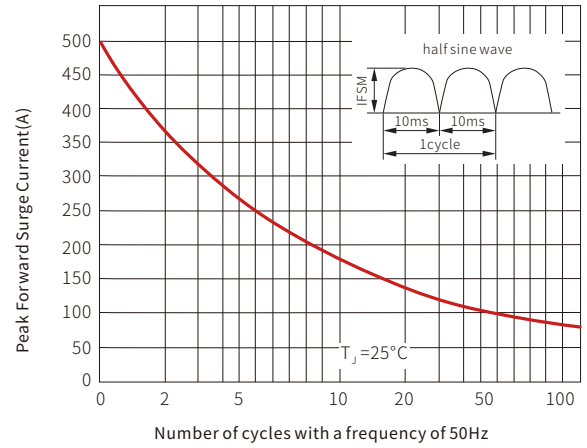


Fig. 3-Typical Reverse Characteristics

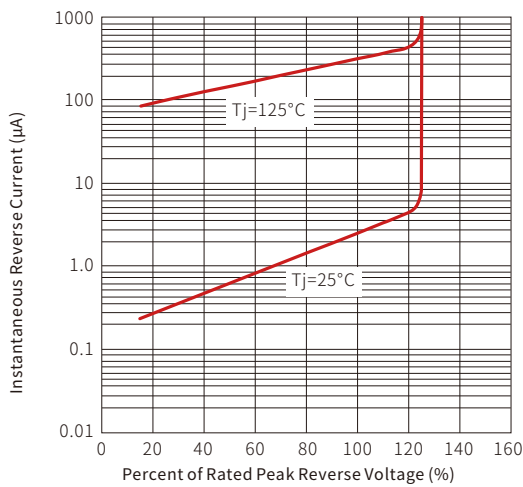
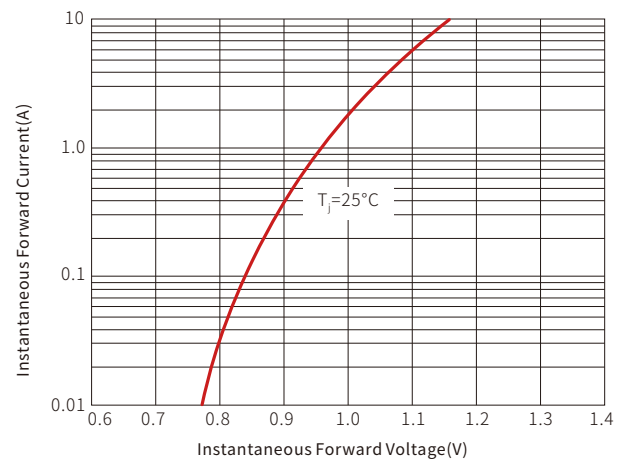
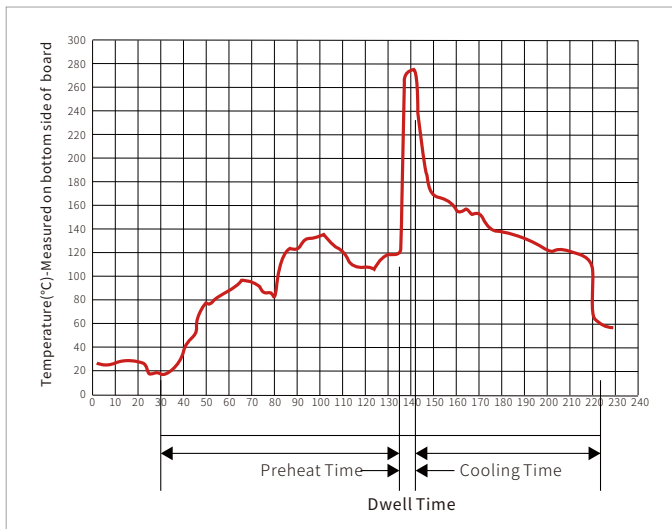


Fig. 4-Typical Forward Characteristics

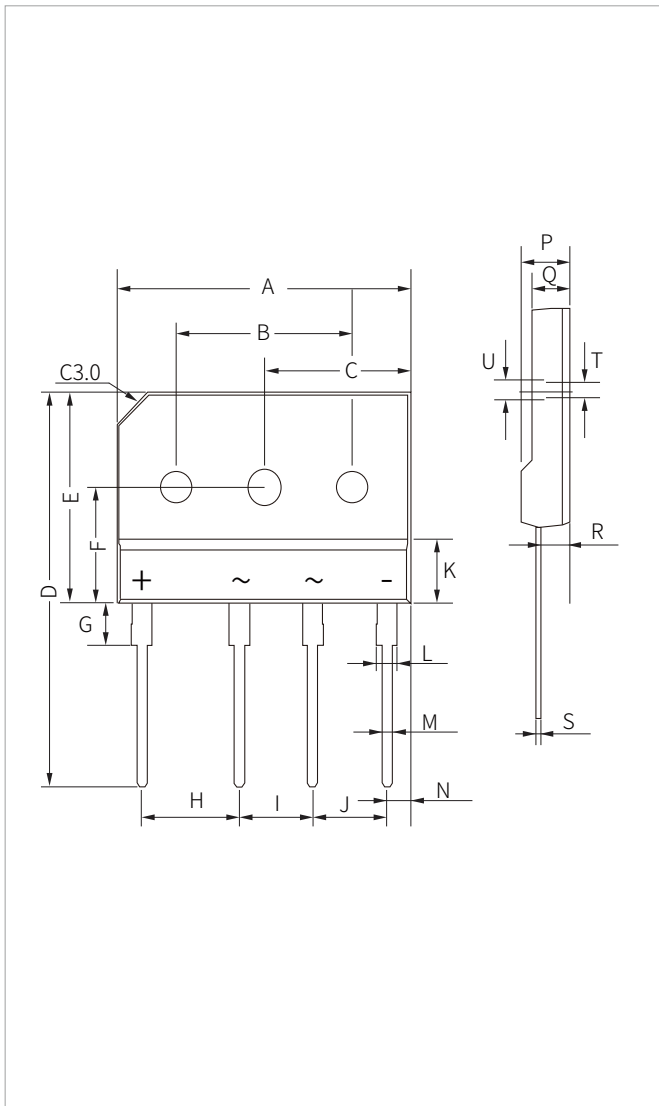


WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

GBJ PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	29.8	30.2	1.173	1.189
B	17.8	18.2	0.701	0.717
C	14.8	15.2	0.583	0.600
D	37.3	37.7	1.469	1.484
E	19.8	20.2	0.780	0.800
F	10.8	11.2	0.425	0.441
G	3.80	4.20	0.150	0.165
H	9.90	10.10	0.390	0.398
I	7.40	7.60	0.291	0.299
J	7.40	7.60	0.291	0.299
K	5.90	6.10	0.232	0.240
L	1.95	2.15	0.077	0.085
M	0.90	1.10	0.035	0.043
N	2.40	2.60	0.094	0.102
P	4.40	4.80	0.173	0.189
Q	3.40	3.80	0.134	0.150
R	2.50	2.70	0.098	0.106
S	0.55	0.75	0.022	0.030
T	3.10	3.30	0.122	0.130
U	3.40	3.60	0.134	0.142

ORDERING INFORMATION

Part Number	Component Package	Per Box	Description
GBJ50005-GBJ5010	GBJ	250PCS	Box

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By QR Code

Website



Wechat

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